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[0042] A method and system for delivering a polishing fluid to a chemical mechanical polishing surface is provided. In one embodiment, the system includes an arm having a delivery portion disposed at least partially over the polishing surface. A first nozzle and a second nozzle are disposed on the delivery portion of the arm. The first nozzle is adapted to flow the polishing fluid at a first rate while the second nozzle is adapted to flow the polishing fluid at a second rate that is different than the first rate. A method for delivering a polishing fluid to a chemical mechanical polishing surface generally includes the steps of supplying the polishing fluid to a semiconductor polishing surface in one location at a first rate and providing the polishing fluid to the polishing surface at a second location at a second rate which is different than the first rate.